

Hiner-pack® MCS-PFA Cassette 150 mm

PFA wafer cassettes for high-purity semiconductor wet processes

PFA wafer cassettes provide unmatched performance in the transfer, storage, and cleaning of semiconductor wafers during high-temperature wet processing and corrosive chemical applications. Molded from high-purity perfluoroalkoxy (PFA) or Teflon resin, these wafer carriers withstand prolonged exposure to strong acids, hydrofluoric acid, and alkaline solutions at temperatures up to 220 °C without warping or contamination. The smooth, translucent surfaces reduce particle generation and enable easy cleaning, safeguarding wafer quality during critical process steps. Compatible with standard wafer handling systems, wet benches, and SMIF/FOUP interfaces, PFA cassettes deliver outstanding chemical resistance, dimensional stability, and ultra-clean performance for advanced wafer etching, cleaning, and processing environments.

SPECIFICATIONS

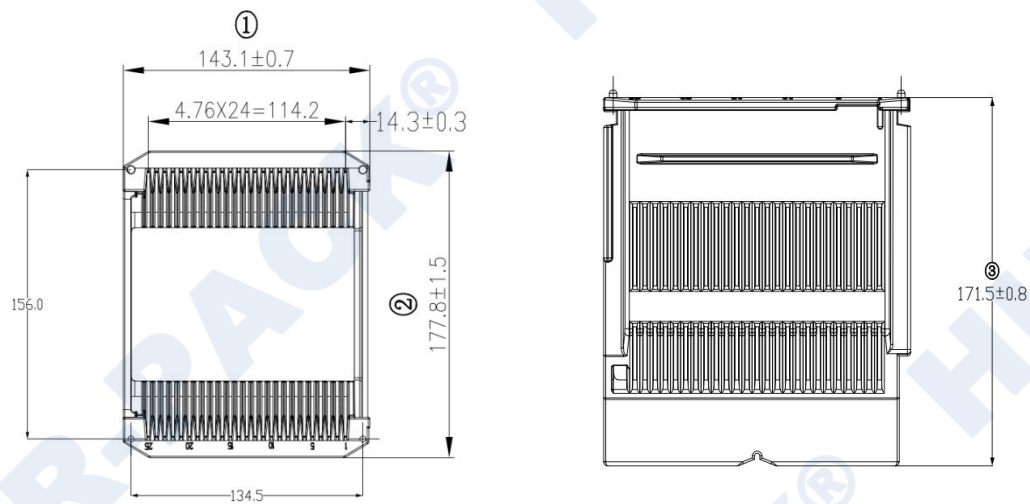
- 177.8 mm L × 143.1 mm W × 171.5 mm H (7" × 5.63" × 6.75")
- Maximum load capacity is 25 pieces

FEATURES & BENEFITS

- Inert PFA/Teflon resists strong acid/base and HF corrosion
- Withstands temperatures up to approximately 220 °C without degradation or deformation
- Smooth/translucent surface simplifies cleaning
- Supports customization (handles, laser engraving, RFID)



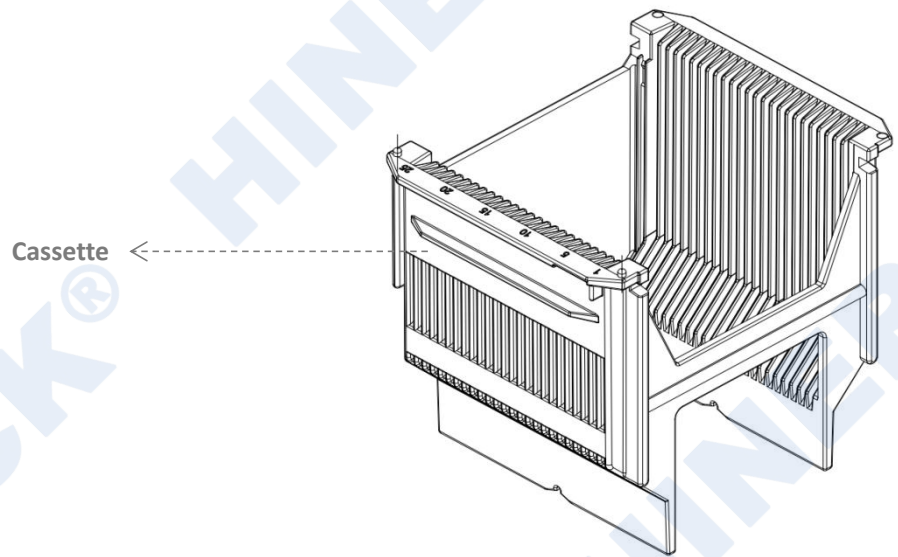
DIMENSION



BASIC INFORMATION

Part Number	Material	Wafer Size
MCS-6/25-NP-PFA	PFA	150 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Specific Gravity	ASTM D-792	2.12~2.17
Water Absorption	ASTM D-570 (24h, 1/3" thick)	<0.01%
Molding Shrinkage	--	0.04 cm/cm
Contact Angle	Angle with Horizontal Surface	115°
Thermal Conductivity	ASTM C-177	--
Coefficient of Linear Thermal Expansion	ASTM D-696 (23~60°C)	12x10 ⁻⁵ /°C
Melting Point	--	302~310 °C
Melt Viscosity	--	10 ⁴ ~10 ⁵ /°C (380°C)
Maximum Continuous Use Temperature	--	380°C
Tensile Strength	ASTM D-638 (23°C)	27~31 MPa
Elongation	ASTM D-638 (23°C)	280~300 %
Compressive Strength	ASTM D-695 (1%deformation, 25°C)	5~6 MPa
Tensile Resilience	ASTM D-638 (23°C)	--
Flexural Resilience	ASTM D-790 (23°C)	647~686 MPa
Impact Strength	ASTM D-256 (23°C, Izod)	--
Hardness	Durometer	D60 shore
Bearing Deformation	ASTM D-621 (100°C, 7MPa, 24h)	2.4 %
	ASTM D-621 (23°C, 14MPa, 24h)	2.7 %
Static Friction Coefficient	Against Steel	0.05

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



Hiner-pack®

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